PCN Number:	20240327006.1	**PCN Date:**	March 28, 2024
Title:	Qualification of RFAB using qualified Process Technology and Die Revision for select devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	June 26, 2024	**Sample requests accepted until:**	April 27, 2024*

***Sample requests received after April 27, 2024 will not be supported.**

Change Type:

☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

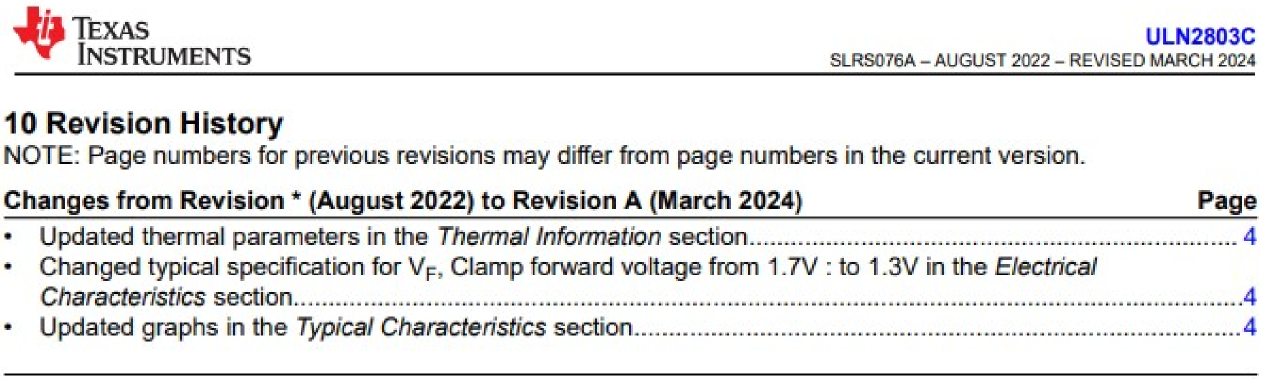
PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the TIB qualified process technology.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
SFAB	JI1	150 mm	RFAB	TIB	300 mm

As a result of the changes described above, there are datasheet changes as per below:



TEXAS INSTRUMENTS

ULN2803C

SLRS076A – AUGUST 2022 – REVISED MARCH 2024

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (August 2022) to Revision A (March 2024)	Page
• Updated thermal parameters in the *Thermal Information* section	4
• Changed typical specification for V_F, Clamp forward voltage from 1.7V : to 1.3V in the *Electrical Characteristics* section	4
• Updated graphs in the *Typical Characteristics* section	4

The datasheet number will be changing.

Device Family	Change From:	Change To:
ULN2803C	SLRS076	**SLRS076A**

These changes may be reviewed at the datasheet links provided.
http://www.ti.com/product/ULN2803C

The die was also changed as a result of the process change.

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current **New**

Die Rev [2P]	**Die Rev [2P]**
-	**A**

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

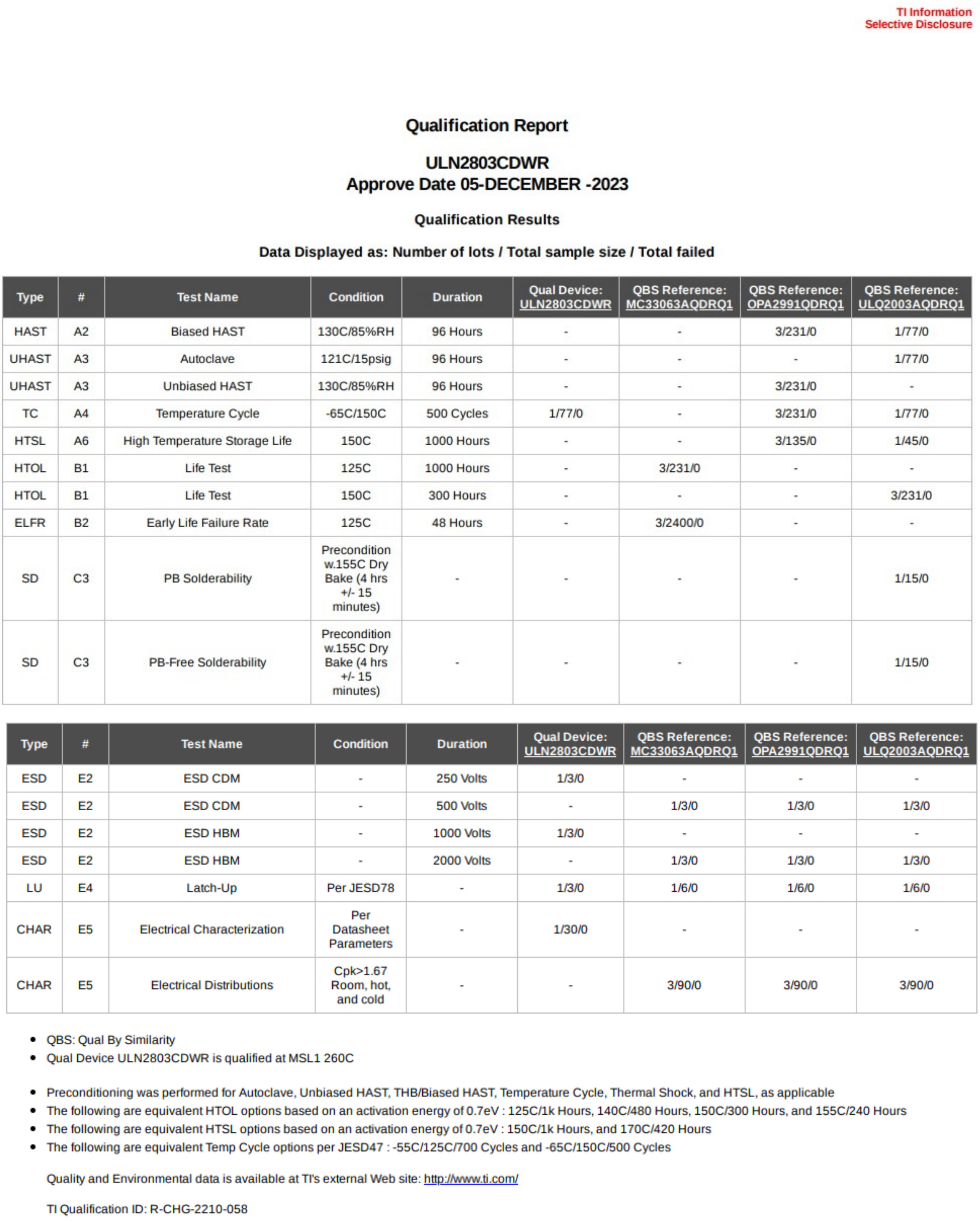
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

ULN2803CDWR

For alternate parts with similar or improved performance, please visit the product page on TI.com



TI Information
Selective Disclosure

Qualification Report

ULN2803CDWR
Approve Date 05-DECEMBER -2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: ULN2803CDWR	QBS Reference: MC33063AQDRQ1	QBS Reference: OPA2991QDRQ1	QBS Reference: ULQ2003AQDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	1/77/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0

Type	#	Test Name	Condition	Duration	Qual Device: ULN2803CDWR	QBS Reference: MC33063AQDRQ1	QBS Reference: OPA2991QDRQ1	QBS Reference: ULQ2003AQDRQ1
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	3/90/0

- QBS: Qual By Similarity
- Qual Device ULN2803CDWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2210-058

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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